



Express Mail No. EV758927645US

Attorney Docket No. 108298749US
Disclosure No. 03-0866.00/USPTO/SB/08a/b (07-05)
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Substitute for form 1449A/B/PTO				Complete If Known	
				Application Number	10/785,466-Conf. #8567
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)				Filing Date	February 23, 2004
				First Named Inventor	Kyle K. Kirby
				Art Unit	2878
				Examiner Name	B. J. Livedalen
Sheet	1	of	6	Attorney Docket Number	108298749US

U.S. PATENT DOCUMENTS						
Examiner Initials*	Cite No. ¹	Document Number		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number-Kind Code ² (if known)				
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BC		US-10/857,948			Boettiger et al.	
BC		US-10/863,994			Akram et al.	
BC		US-10/864,974			Kirby et al.	
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Examiner Signature	<i>B. J. Livedalen</i>	Date Considered	2/17/06
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Examiner Signature	<i>Brian T. Mc</i>	Date Considered	2/17/06
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<i>R/K</i>	FR-2 835 654-A1	08-08-2003	STMicroelectronics SA		
<i>R/K</i>	WO-2004/054001-A2	06-24-2004	Augusto		

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NON PATENT LITERATURE DOCUMENTS			
Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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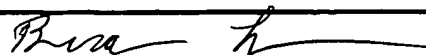
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹Applicant's unique citation designation number (optional). ²Applicant is to place a check mark here if English language Translation is attached.

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